



LUND
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EITF35: Introduction to Structured VLSI Design

Part 1.1.2: Introduction (Digital VLSI Systems)

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Outline

□ Why **Digital**?

- Advantages
- Some applications

□ History & Roadmap

□ Device Technology & Platforms

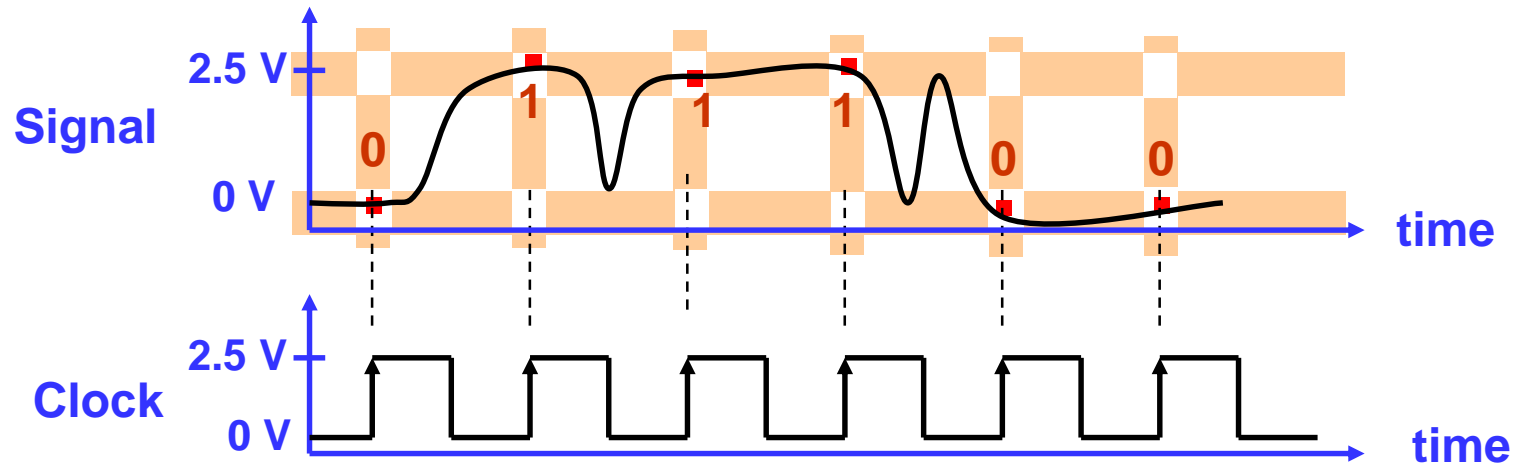
□ System Representation

□ Design Flow

□ RTL Basics



Digitalization



□ Digital is an abstraction

- Discrete in time: **Sampling**
- Discrete in value: **Quantization**

□ Digital vs. Analog

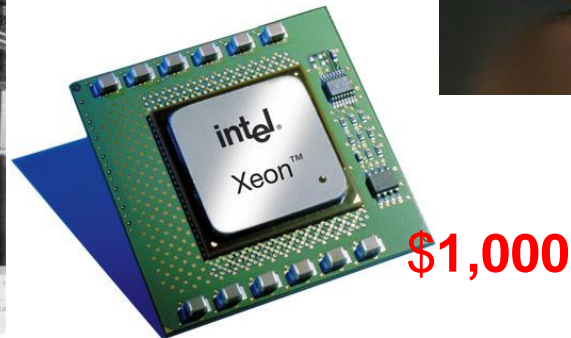
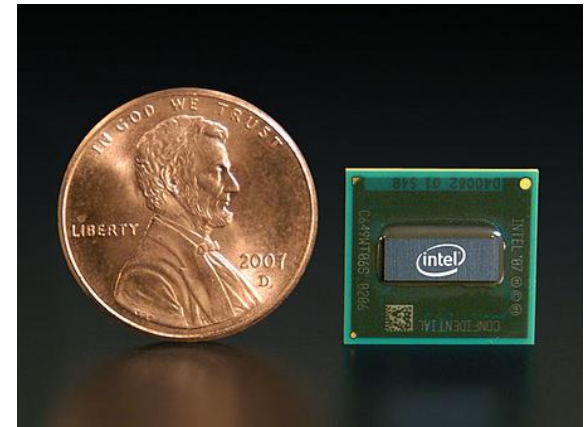
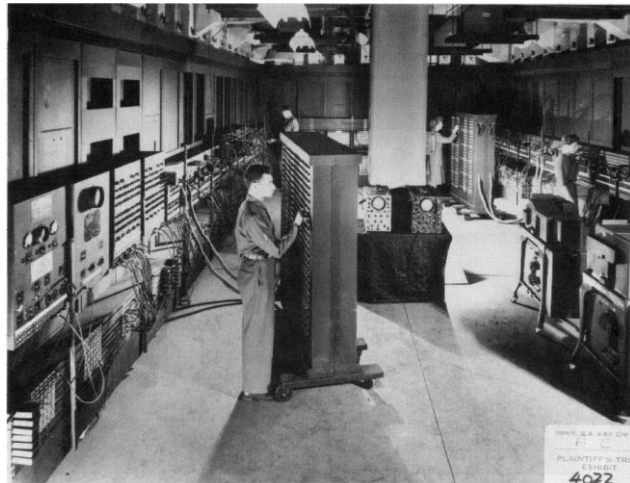
- Flexibility & functionality: easier to store and manipulate information
- Reliability: tolerant to noise, mismatch, variations, etc.
- Economic: easy to design, and friendly to technology evolution
- **Analog interface** is needed



Applications 4C:CCCC



Computation



Applications: CCCC



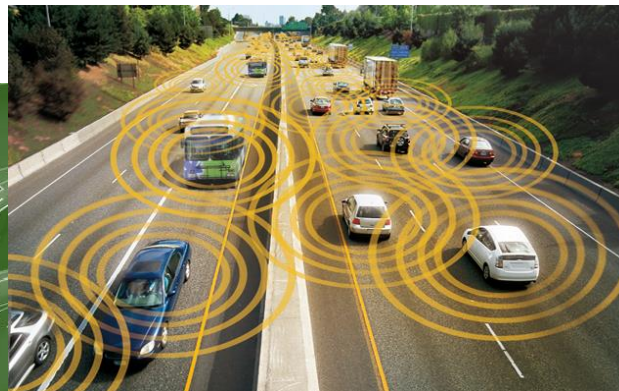
Communication



Applications: CCC



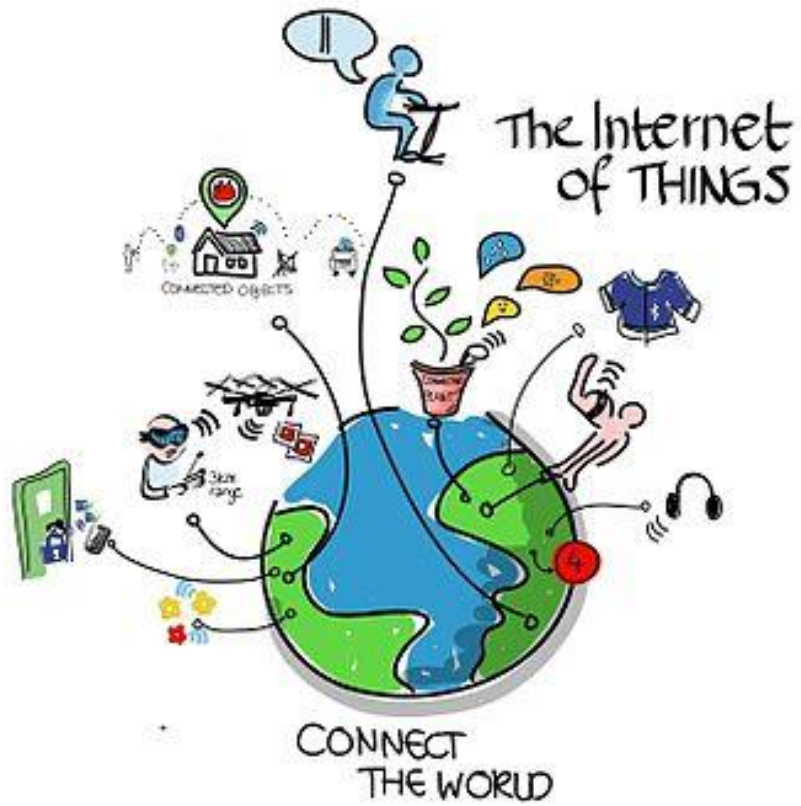
Consumer



Control



Trends



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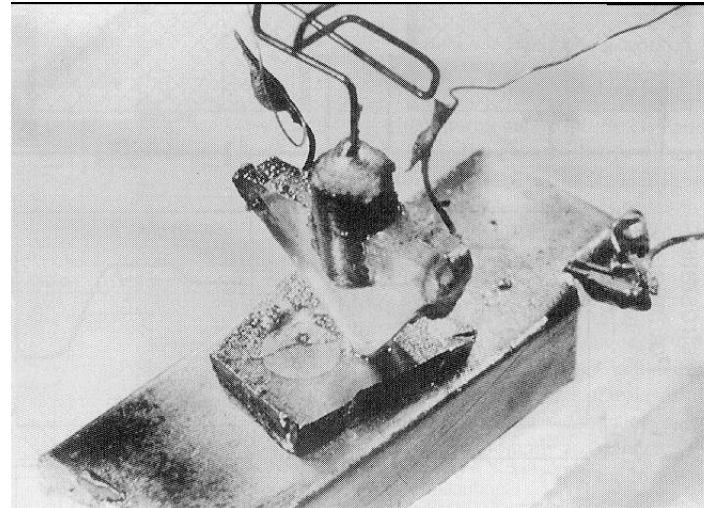
□ RTL Basics



Brief History

□ Transistor Evolution

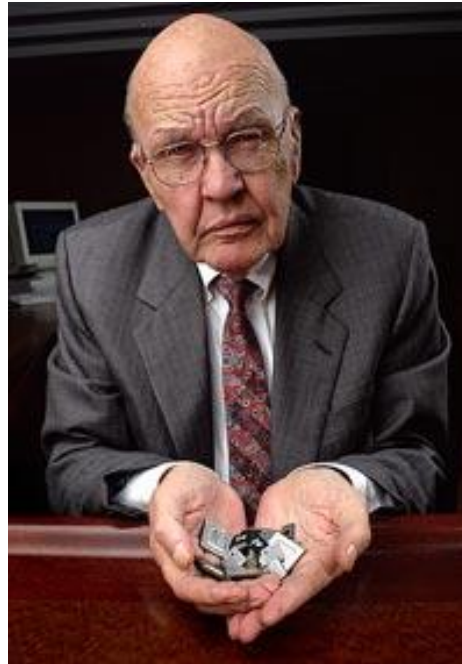
- First Transistor
 - *Bell Labs (1947)*
 - *Bardeen, Brattain, Shockley*
 - *Nobel Prize (1956)*



Brief History

□ Integration Evolution

- First Integrated circuit
 - *Jack Kilby*
 - *TI (1960)*
 - *Nobel Prize (2000)*



“a body of semiconductor material ... wherein all the components of the electronic circuit are completely integrated.”



Technology Evolution

□ Bipolar

- Transistor
 - 1947, *Bardeen/Bell Lab*
- Bipolar junction transistor
 - 1949, *William Shockley*
- Logic gate
 - 1956, *Harris*
- Integrated circuit
 - 1958, *Kilby/Noyes*
- Transistor–transistor logic (TTL)
 - 1962, *James L. Buie*
- High-speed Emitter-coupled logic (ECL)
 - 1974, *Masaki*

□ MOSFET (metal-oxide-semiconductor field-effect transistor)

- Bipolar faces **power** and **size** limitation
- **CMOS logic gate**
 - 1963, *Wanlass*
- PMOSFET
 - 1970, *first practical MOS IC, Calculator*
- NMOSFET
 - 1970, *high-density storay(4K)*
 - 1972, *first microprocessor(4004)*
 - 1974, *8080 microprocessor*



Technology Evolution (cont.)

□ Main trend today

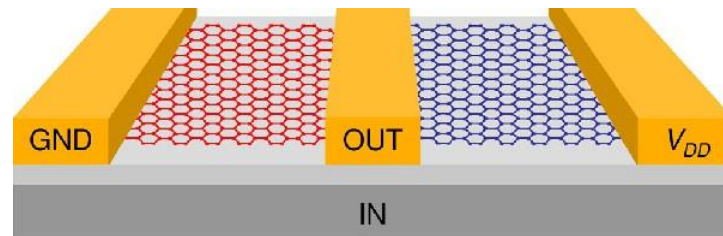
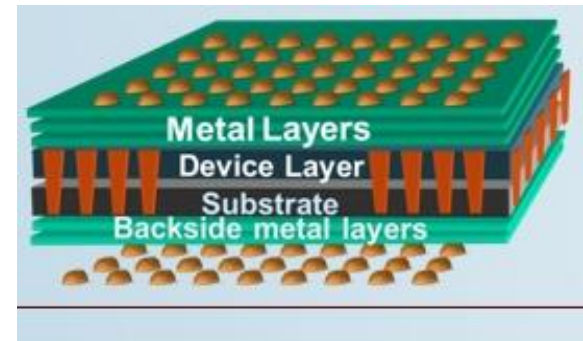
- Since early 80' s until today, **CMOS** became dominant.
- Again, **power consumption** is now becoming a problem.

□ For higher performance, other technologies are used

- Bi-CMOS (bipolar-CMOS): High speed memory and gate arrays.
- ECL (Emitter-coupled logic): Even higher performance.
- SOI (Silicon on insulator): high-performance radio frequency (RF) and radiation-sensitive applications

□ What's Next?

- **3D-IC, FinFET**
- Integrated photonics circuit
- Superconducting electronics
- Quantum circuit
- **Graphene circuit**



Moore's Law

The experts look ahead

Cramming more components onto integrated circuits

With unit cost falling as the number of components per circuit rises, by 1975 economics may dictate squeezing as many as 65,000 components on a single silicon chip

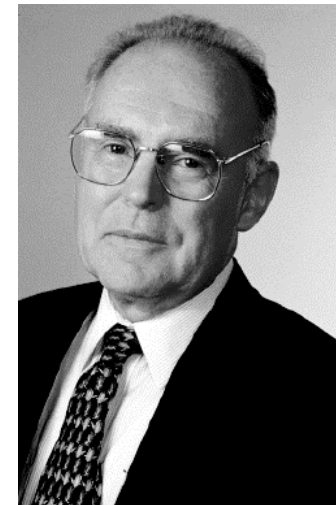
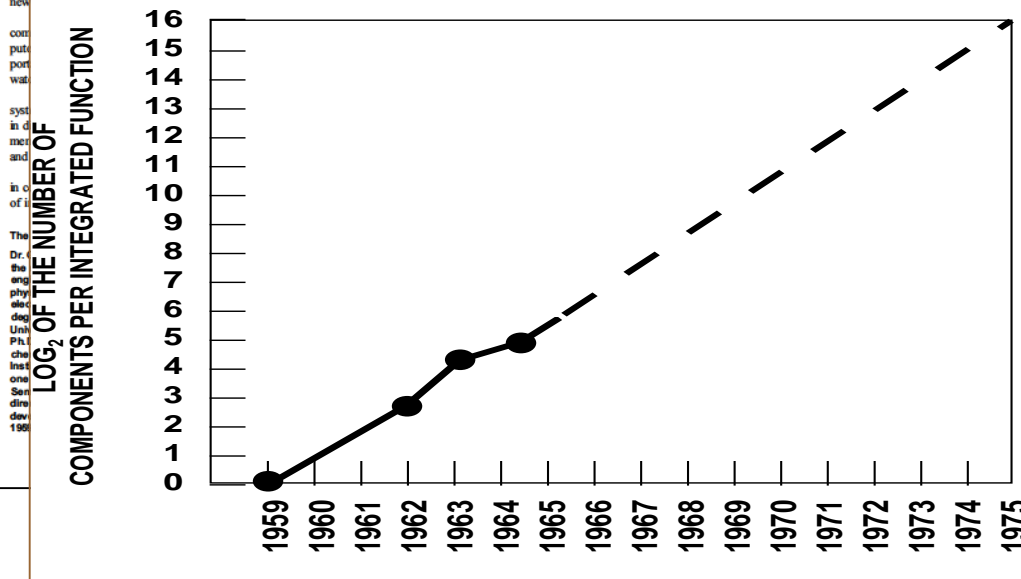
By Gordon E. Moore

Director, Research and Development Laboratories, Fairchild Semiconductor division of Fairchild Camera and Instrument Corp.

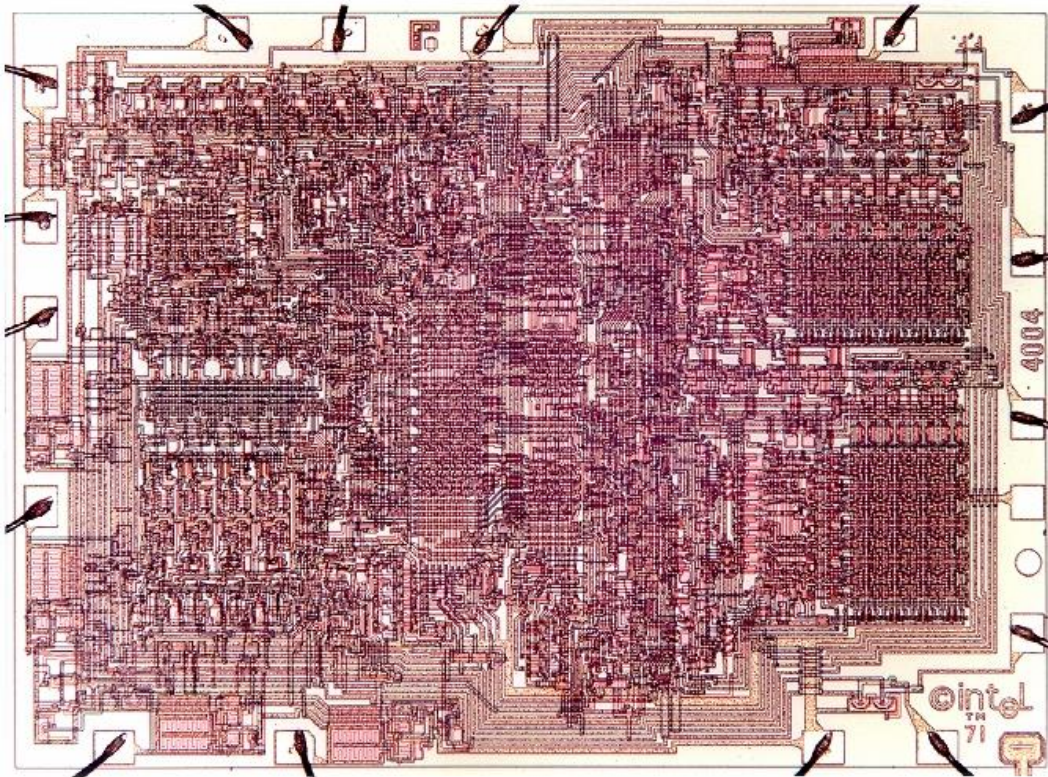
The future of integrated electronics is the future of electronics itself. The advantages of integration will bring about a proliferation of electronics, pushing this science into many new machine instead of being concentrated in a central unit. In addition, the improved reliability made possible by integrated circuits will allow the construction of larger processing units.

□ Electronics, Apr. 19, 1965

Gordon Moore (co-founder of Intel) made a prediction that semiconductor technology will double its effectiveness every 18 months



Intel 4004:1972

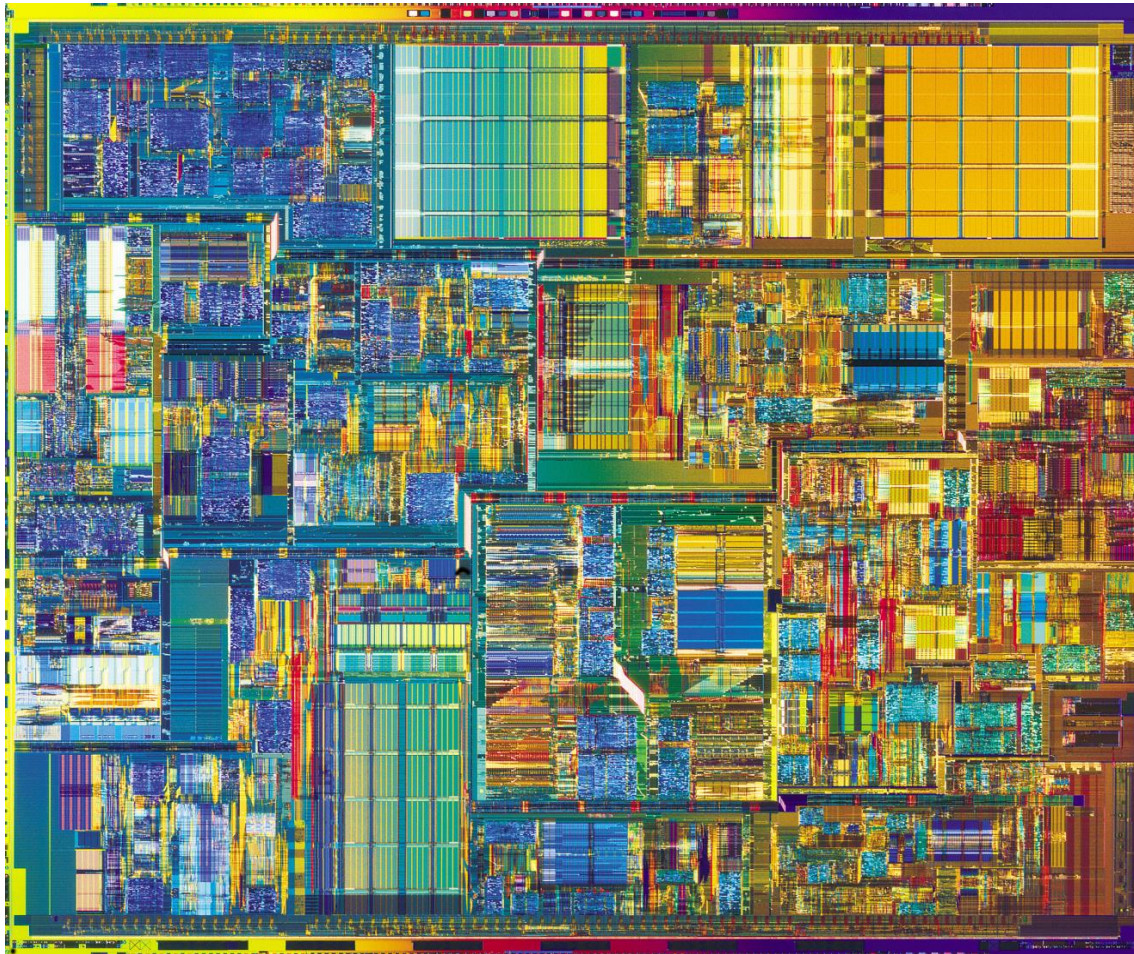


- First micro-processor on a single chip
- 2 300 transistors
- 0.3 mm x 0.4 mm
- 4 bit words
- Clock: 0.108 MHz

You will have the possibility to design a more powerful processor in one of our courses



Intel Pentium 4 (2000)

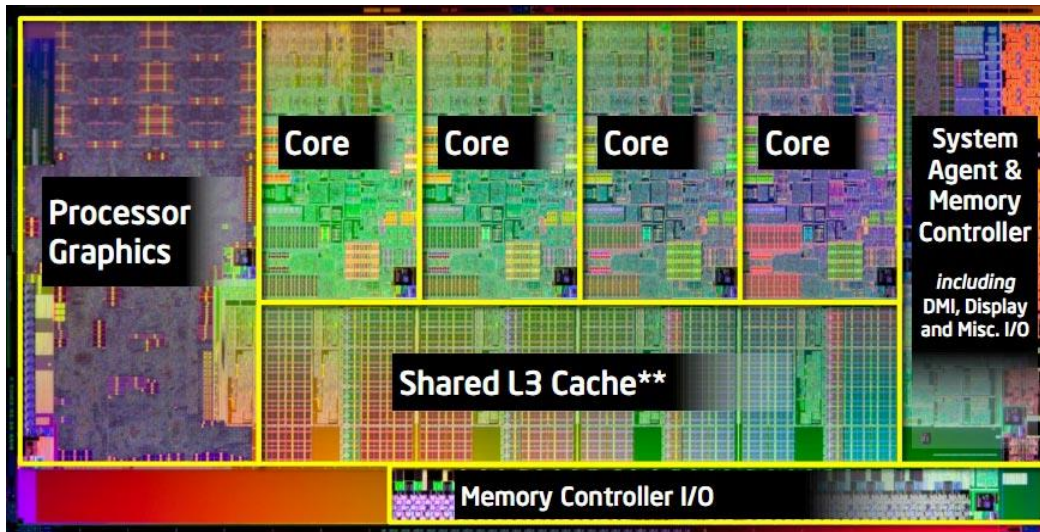


- ❑ 42 000 000 transistors
- ❑ 0.18 micron CMOS
- ❑ Clock: 1.5 GHz
- ❑ Die: 20 mm²

Baseband ASIC of a modern mobile phone has easily 10 times more transistors.

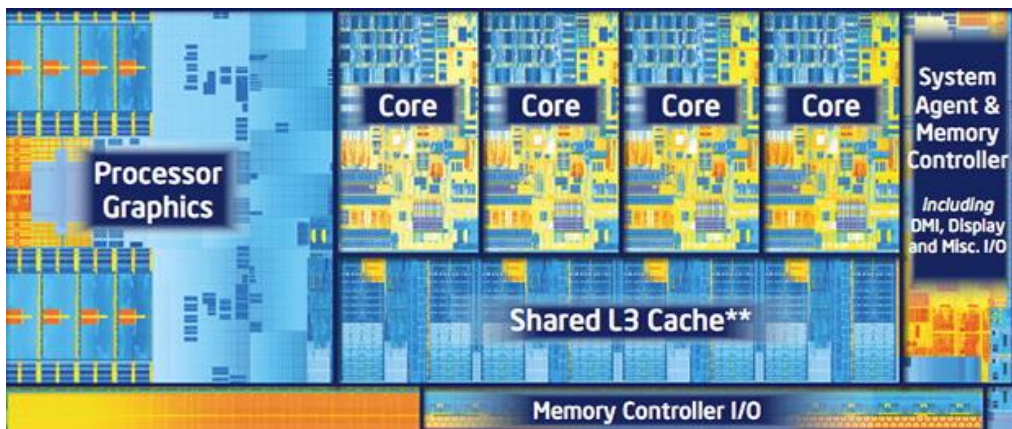


SandyBridge (2009)



- 32 nm-64 bit
- 995 000 000 Transistors (**23 × P4**)
- ~**3.5 GHz**
- 216 mm²

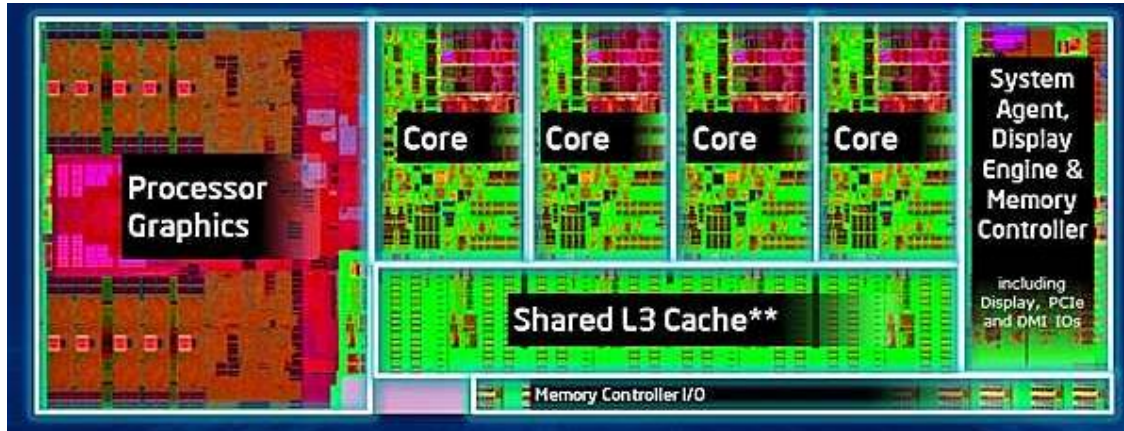
IvyBridge (2011)



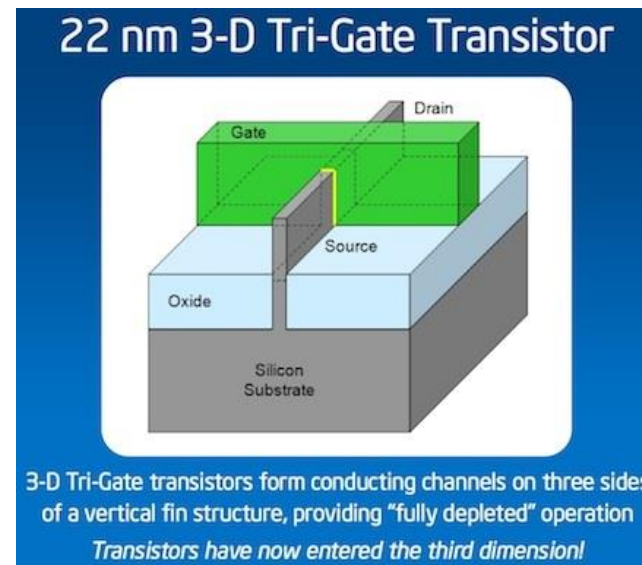
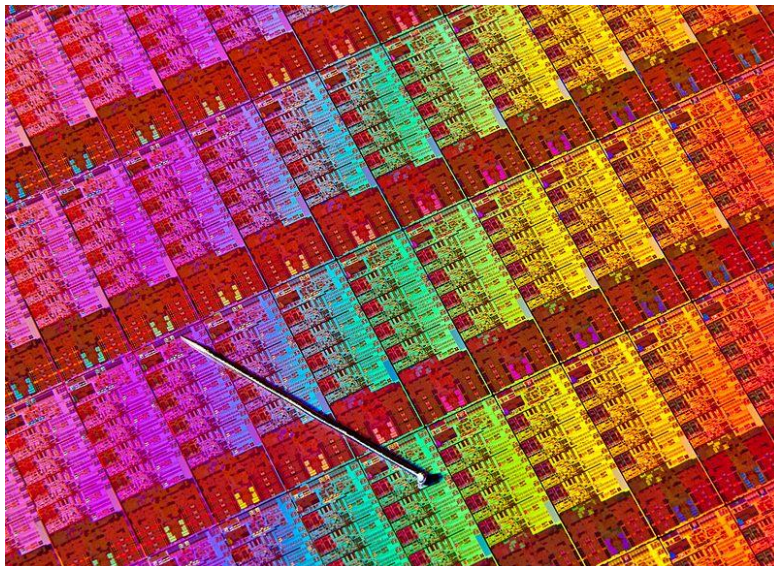
- 22 nm-64 bit
- 1 400 000 000 Transistors
- ~**3.5 GHz**
- 160 mm²



Haswell (2013)



- 22 nm
- **Tri-gate 3D transistor**
- **1.4b Transistors**
- **~3.5 GHz**
- **177 mm²**



Braswell (coming 2015)



The diagram is set against a blue background. On the left, a vertical double-headed blue arrow indicates a spectrum of products. In the center, four processor chips are arranged in a 2x2 grid. The top row is labeled 'Today' and the bottom row is labeled 'Future'. The top-left chip is labeled 'Haswell', the top-right is 'Broadwell', the bottom-left is 'Bay Trail', and the bottom-right is 'Braswell'. Below the chips are four icons: the Android robot, the Chrome logo, the Linux Tux penguin, and the Windows logo. To the right of the grid, the text '5th Generation Core™ Processors' is written in yellow. Below this, three lines of white text describe the processors: 'Industry Leading 14nm', 'Fanless 2 in 1s to Enthusiast Desktops', and 'Amazing Form Factors New User Experiences'.

Today Future

intel Haswell intel Broadwell

intel Bay Trail intel Braswell

5th Generation Core™ Processors

Industry Leading 14nm

Fanless 2 in 1s to Enthusiast Desktops

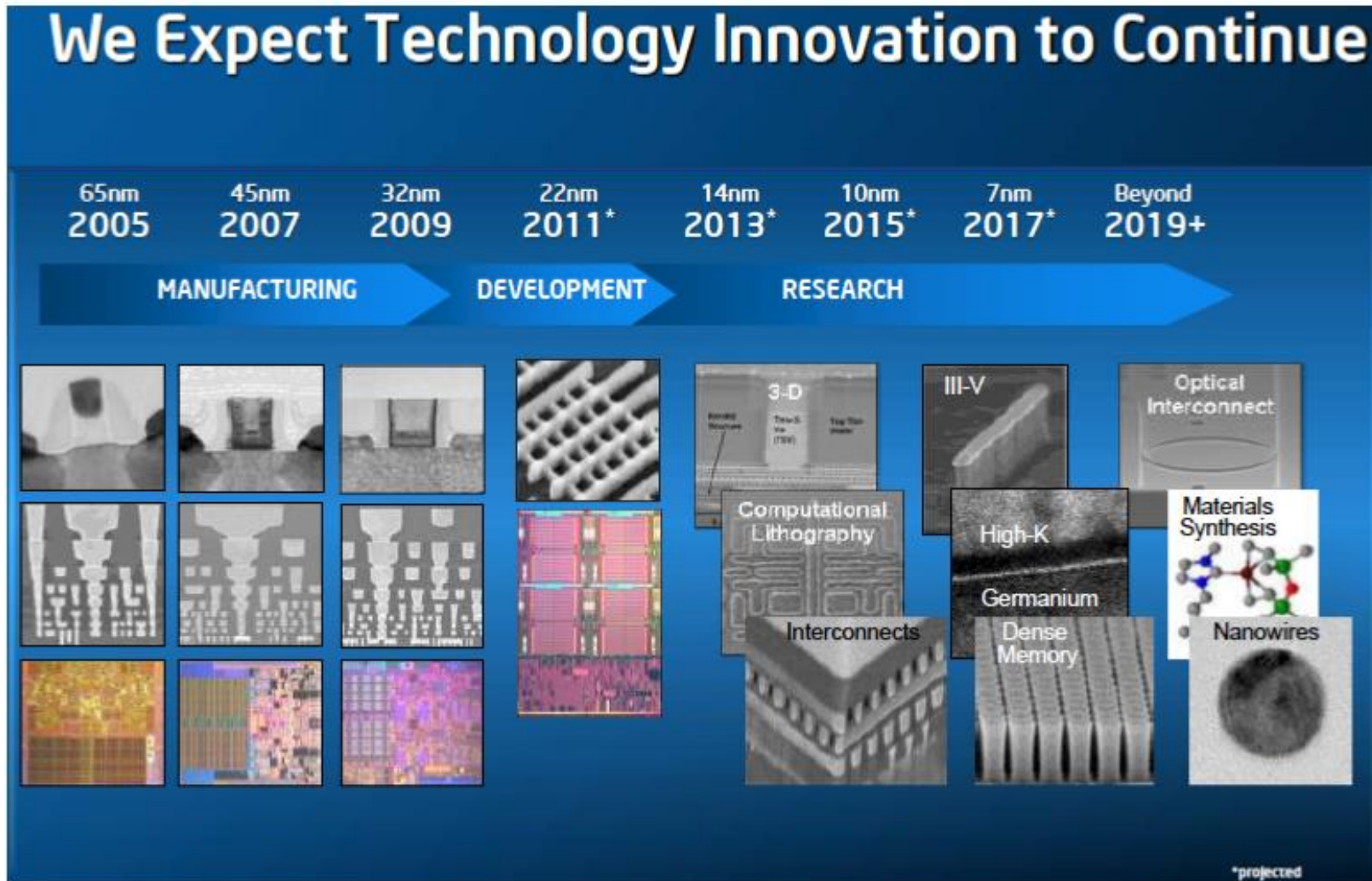
Amazing Form Factors

New User Experiences

Android Chrome Linux Windows

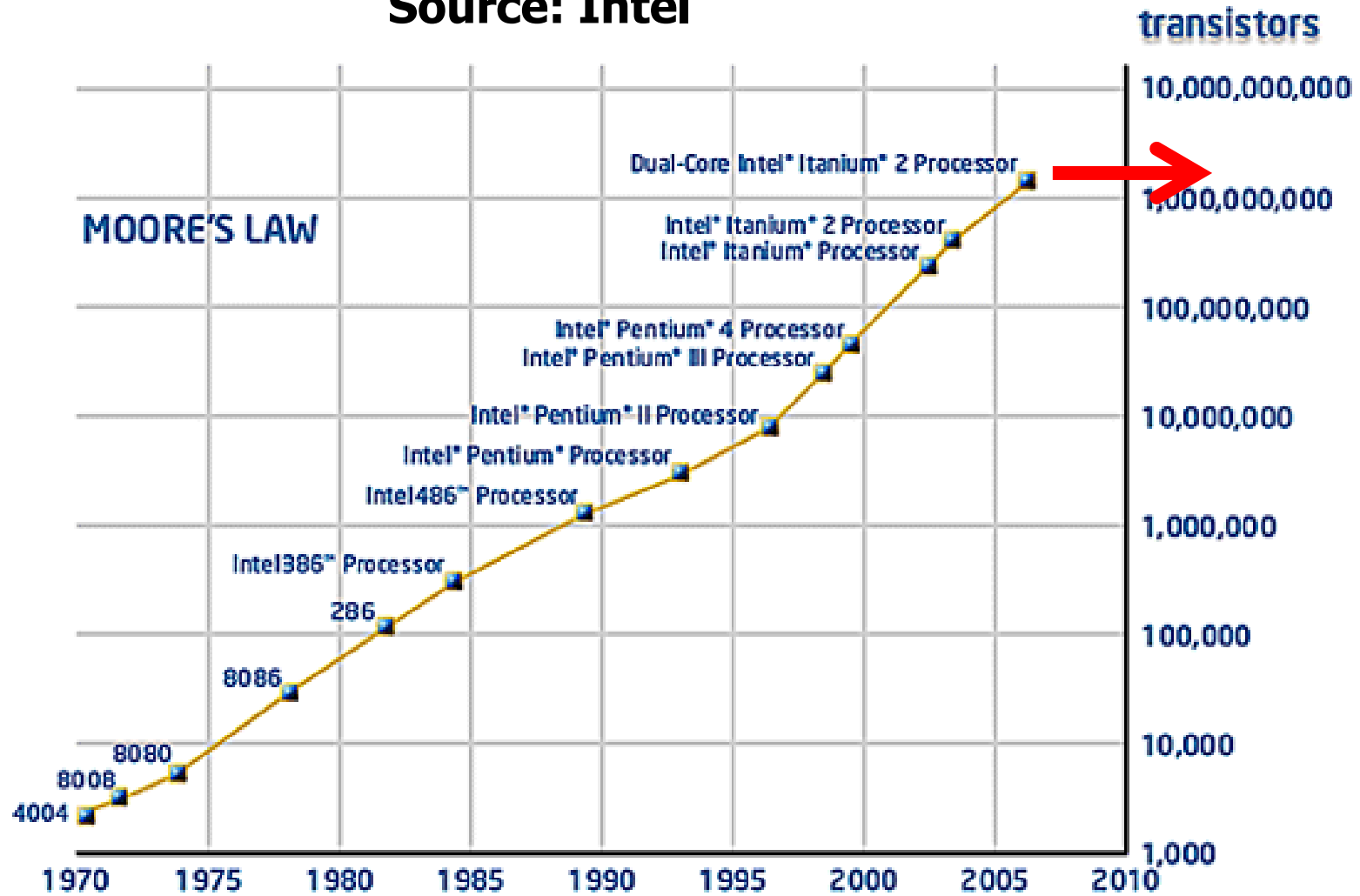


On-Time 2 Year Cycles



Moore's Law: number of transistors

Source: Intel

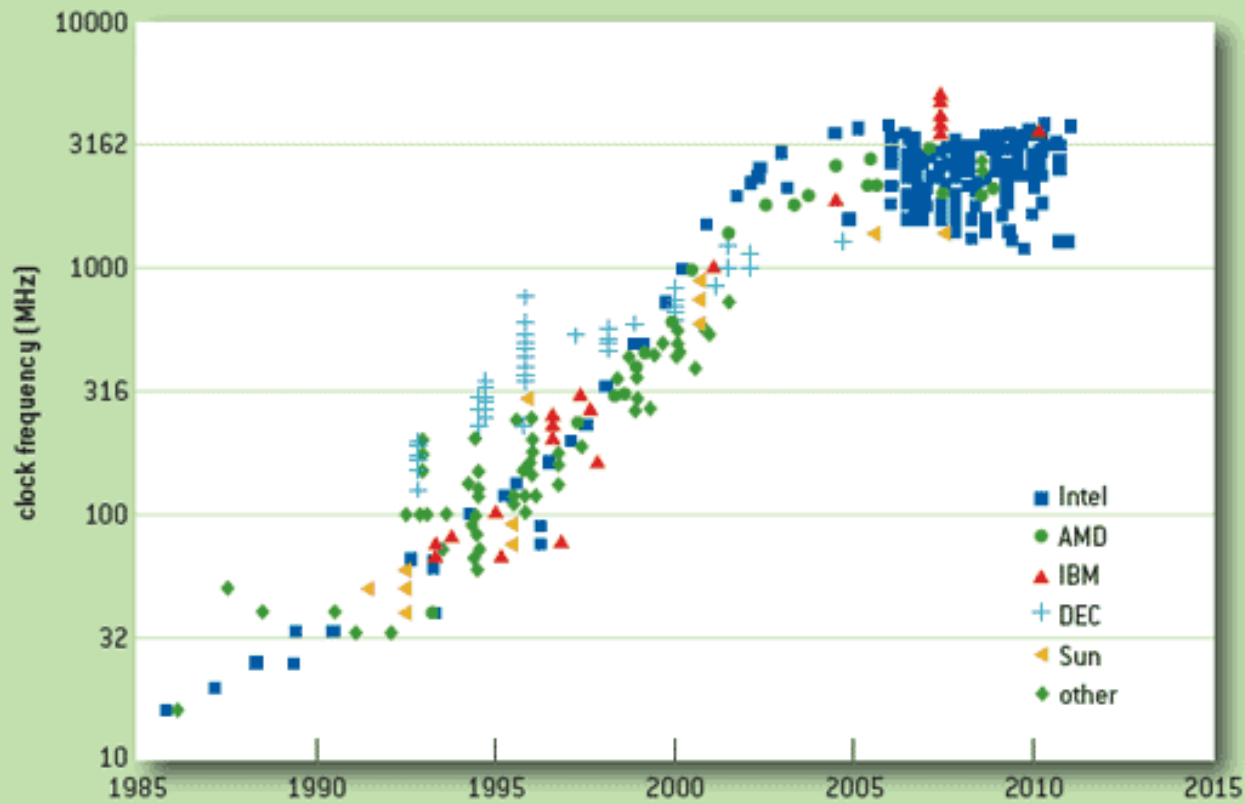


Moore's Law: frequency

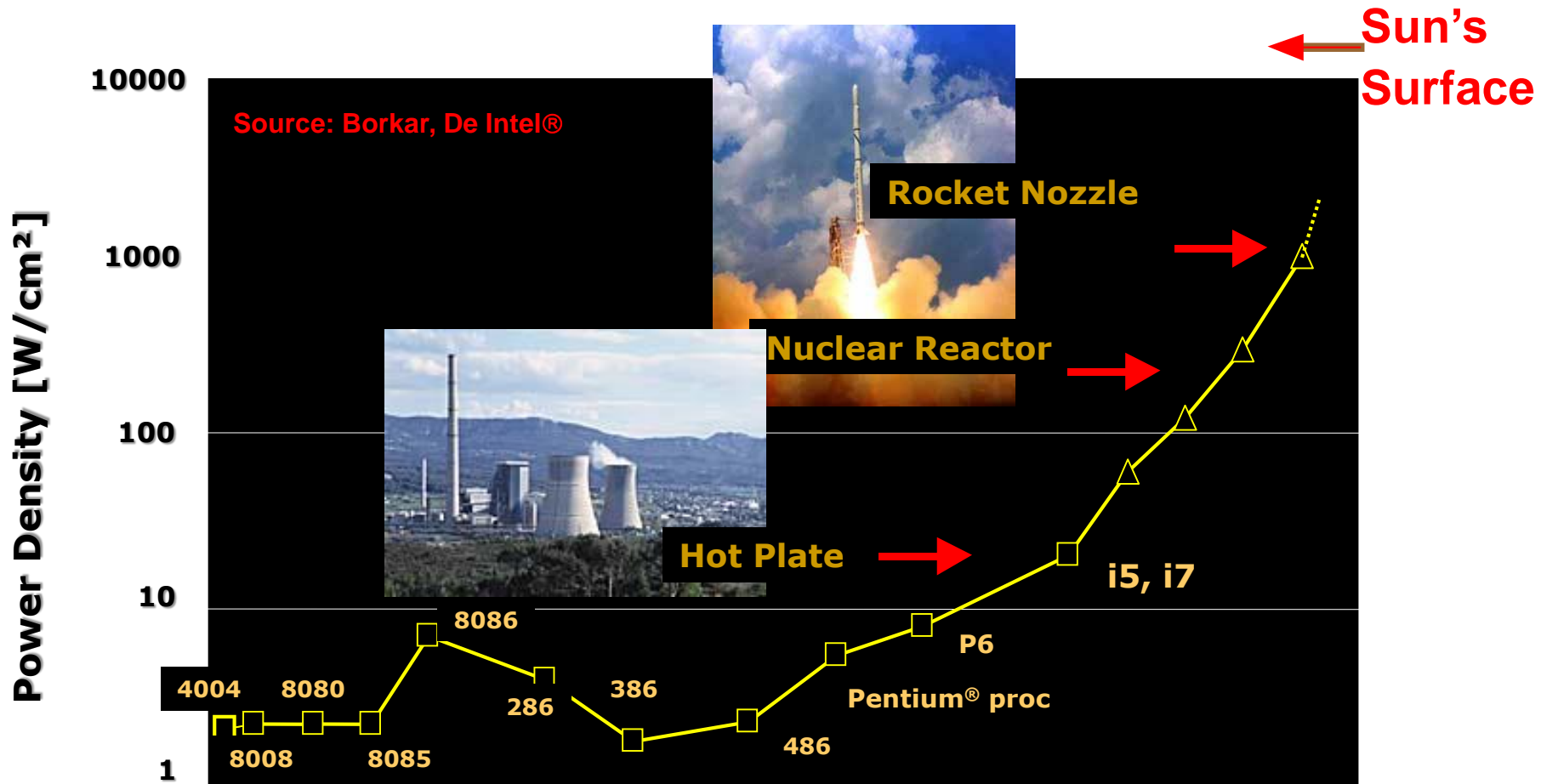
FIGURE 7

Source: CPU DB: Recording Microprocessor History

Processor Frequency Scaling Over Time



Moore's Law: power density



ITRS: The International Technology Roadmap for Semiconductors

- ❑ Published every two years (current 2013)
- ❑ Wide range: material, fabs, equipment, EDA, design, testing, modeling, simulation.....
- ❑ Closely followed by industry: Not an empty prediction, but an actual planning

<http://public.itrs.net/>

EECA

JEITA

KSTIA



SIA

TSIA



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□ Why Digital?

- Advantages
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□ History & Roadmap

□ **Device Technology & Platforms**

□ System Representation

□ Design Flow

□ RTL Basics



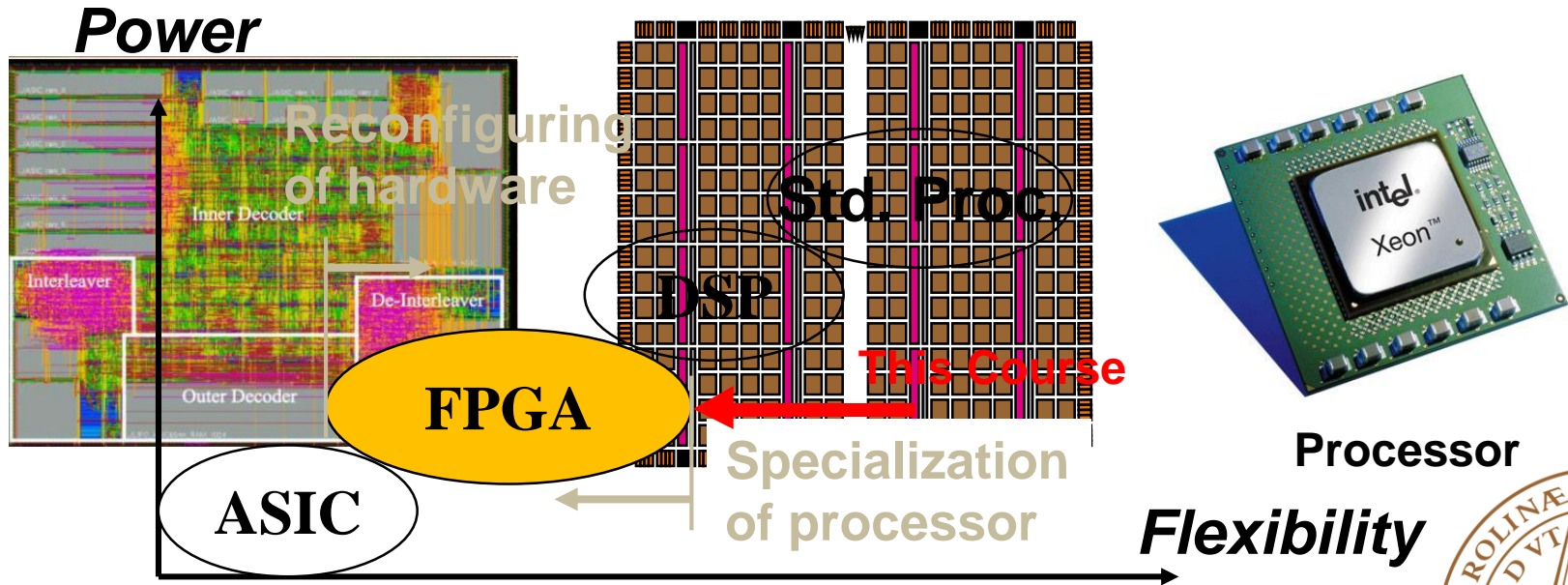
Devices

□ General-purpose integrated circuits

- Microprocessors, digital signal processors, *FPGA* and memories

□ Application-specific integrated circuits (ASIC)

- Designed for a narrow range of applications
- Full-custom ASIC
- *Standard-cell ASIC*



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System Representation

□ System

- SoC: a CPU chip ...

□ Module

- Macro cell in a chip: ALU...

□ Gate

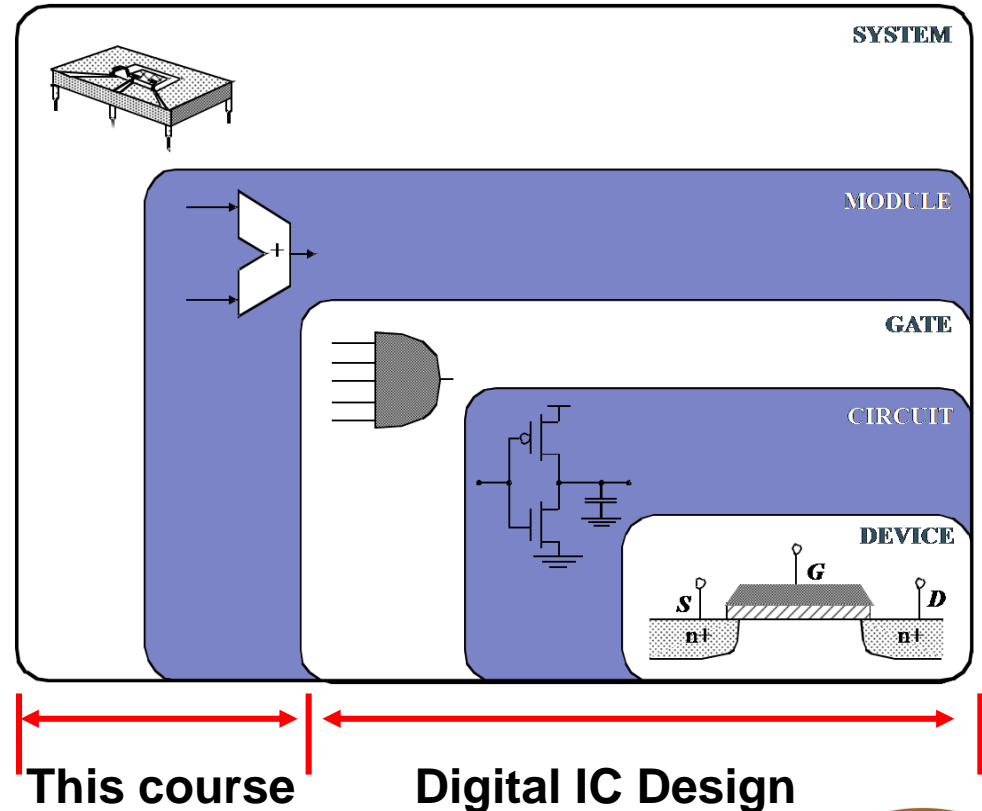
- Basic logic block: xor, nor...

□ Circuit

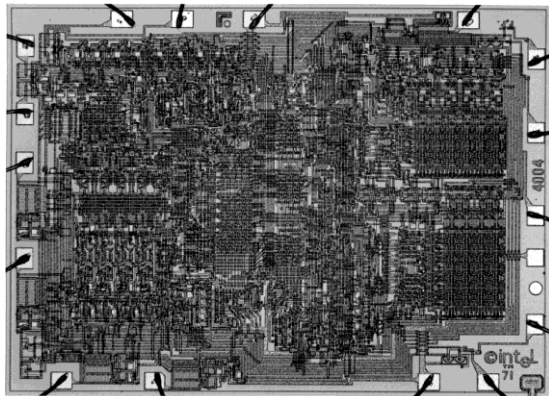
- Transistors

□ Device

- Gate, source, drain

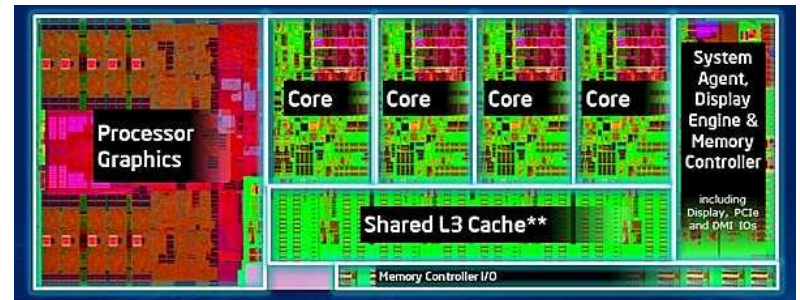


View a Design in a Proper Way



Intel 4004 (2.3K transistors)

Full-custom

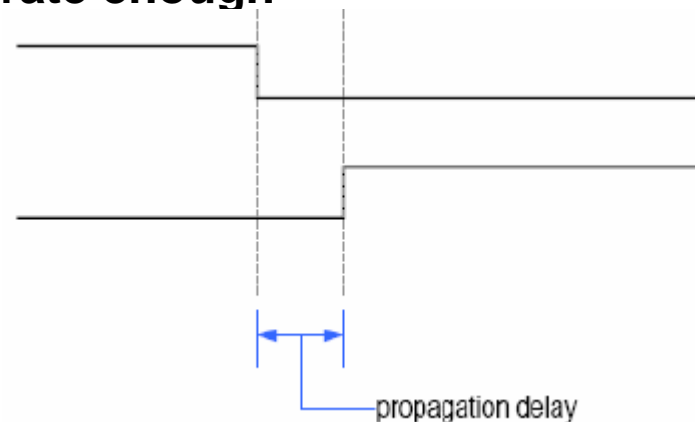
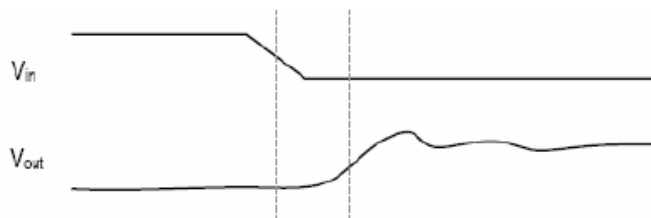


Intel Haswell (1.4B transistors)

?

□ Abstraction: simplified model of a system

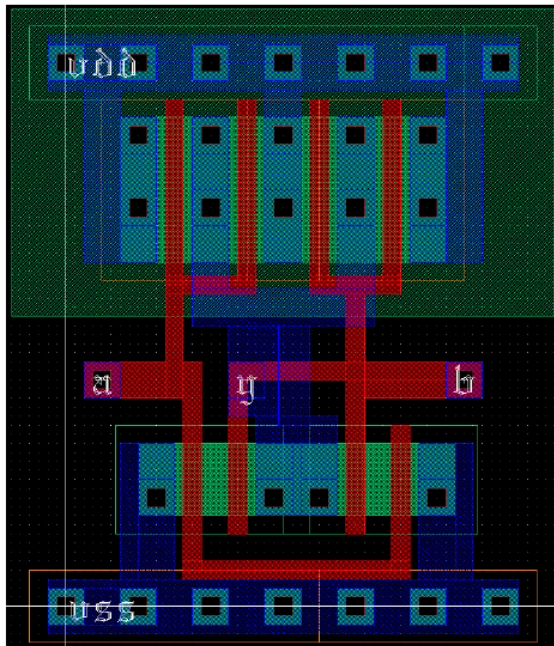
- Show the selected features accurate enough
- Ignore the others



VLSI Design Flow

□ Evolution of circuit design

- Full-custom \Rightarrow Design-automation
 - *Based on library cells and IPs*
 - *Top-down methodology*
- Design abstraction \Rightarrow “Black box” or “Model”
 - *Parameter simplification*
 - *Accurate enough to meet the requirement*



```
module HS65_GH_NAND2AX14 (Z, A, B);  
    output Z;  
    input A,B;  
    not U1 (INTERNAL1, B) ;  
    or #1 U2 (Z, A, INTERNAL1) ;  
    specify  
        (A +=> Z) = (0.1,0.1);  
        (B -=> Z) = (0.1,0.1);  
    endspecify  
endmodule // HS65_GH_NAND2AX14
```



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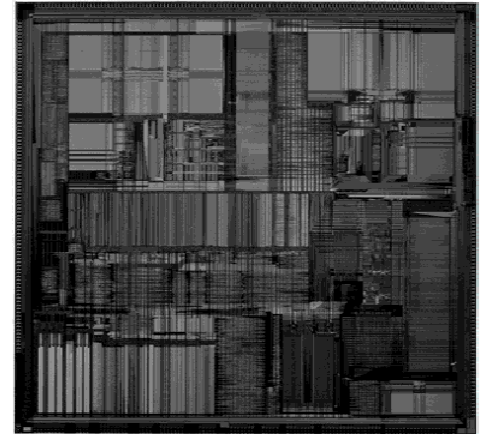
□ RTL Basics



VLSI Design

□ Set of specification:

- What does the chip **do**?
- How **fast** does it run?
- How **reliable** will it be?
- How is the silicon **area**?
- How much **power** will it consume?
-

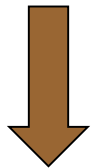


VLSI Design Flow

- An iterative process that transfer the specification to a manufacturable chip through at least five levels of design abstraction.

Specification

Function, performance, definition:
English

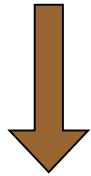


Behavior Design

Behavior, algorithm: C/C++, SystemC,
Matlab ...

Behavior simulation

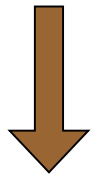
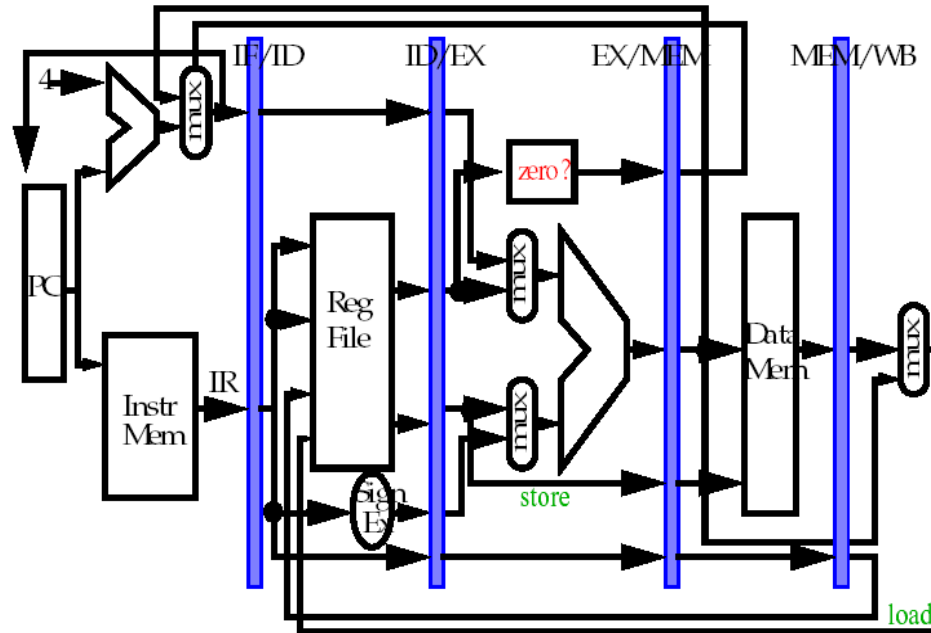




VHDL
Verilog

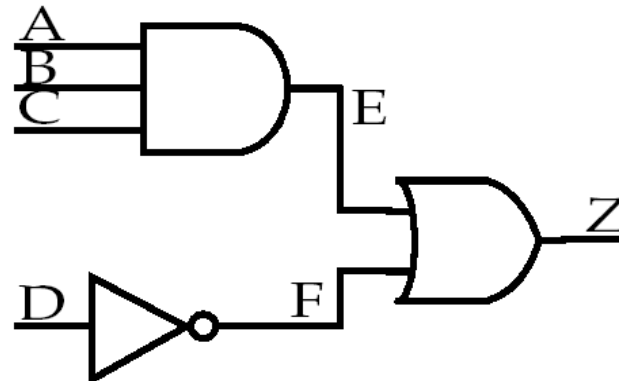
Register Transfer
Level Design

RTL simulation



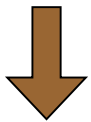
Synthesis

Logic Design



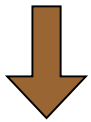
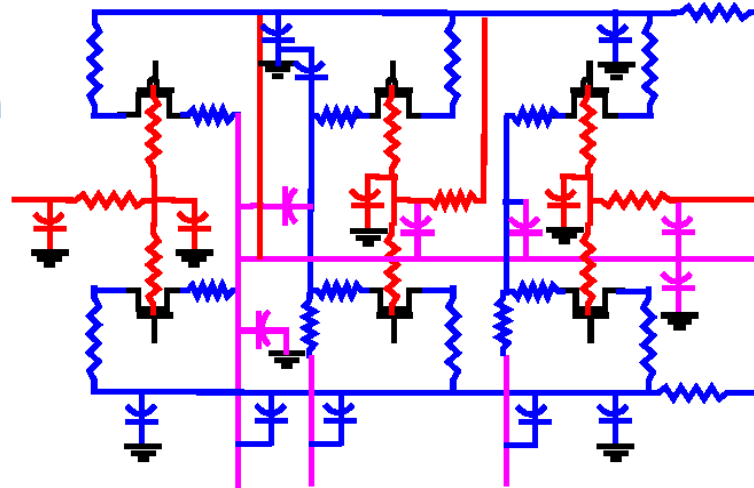
Gate-level simulation
Timing analysis
Power analysis





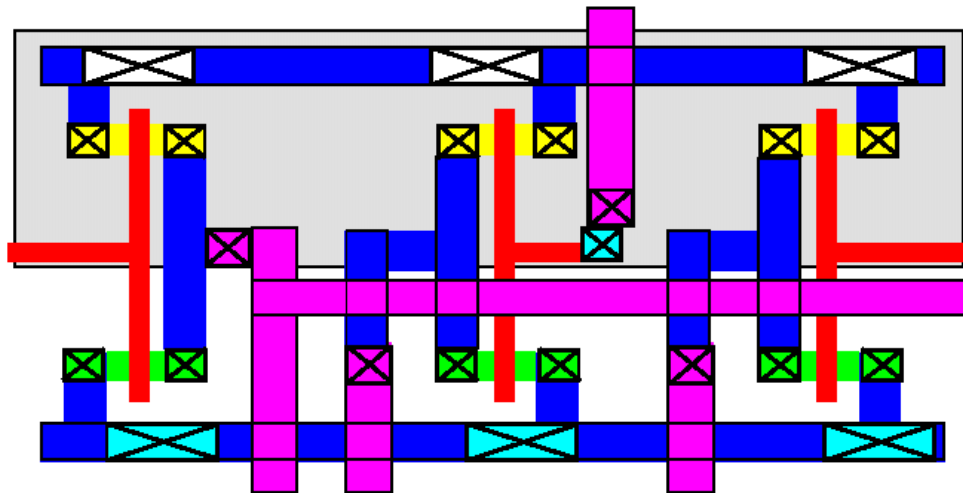
Custom Design

Circuit Design



Layout

Physical Design



Design rule checking
Post layout simulation



Verification

□ Verification

- Check whether a design meets the **specification** and **performance goals**
- Concern the correctness of the initial design and the refinement

□ Two aspects

- **Functionality**
- **Performance (timing)**

□ Method of Verification

- **Simulation**
 - *Spot check: cannot verify the absence of errors*
 - *Can be computation intensive*
- **Timing analysis**
 - *Just check delay*
- Formal verification
 - *Apply formal math techniques determine its property*
 - *E.g, equivalence checking*
- **Hardware emulation**



Fabrication

22nm Fab Upgrades

D1D/C
Oregon



Fab 32/12
Arizona



Fab 28
Israel



14nm and Beyond

D1X
Oregon



Fab 42
Arizona

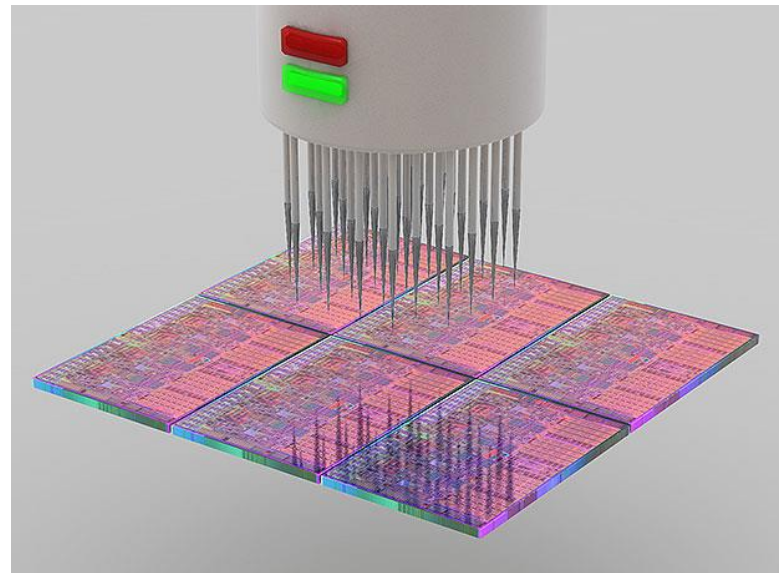


Fab 24
Ireland



Testing

- Testing is the process of detecting physical defects of a die or a package occurred at the time of manufacturing
- **Testing** and **verification** are different tasks.
- **Difficult for large circuit**
 - Need to add auxiliary testing circuit in design
 - E.g., built-in self test (BIST), scan chain etc.



VLSI Design Flow: Tools

□ Algorithm

- **Matlab**

□ RTL Simulation

- **Modelsim, Mentor**
- VCS, Synopsys
- VerilogXL, Cadence

□ Logic Synthesis

- **Design Compiler, Synopsys**
- Blast Create, Magma

□ Transistor Simulation

- Hspice/Starsim, Synopsys
- Spectra, Cadence
- Eldo, Mentor

□ Mixed-Signal Simulation

- **AMS Designer, Cadence**
- ADMS, Mentor
- Saber, Synopsys

□ Place & Route

- Astro, Synopsys
- **Silicon Encounter, Cadence**
- Blast Fusion, Magma

□ Layout

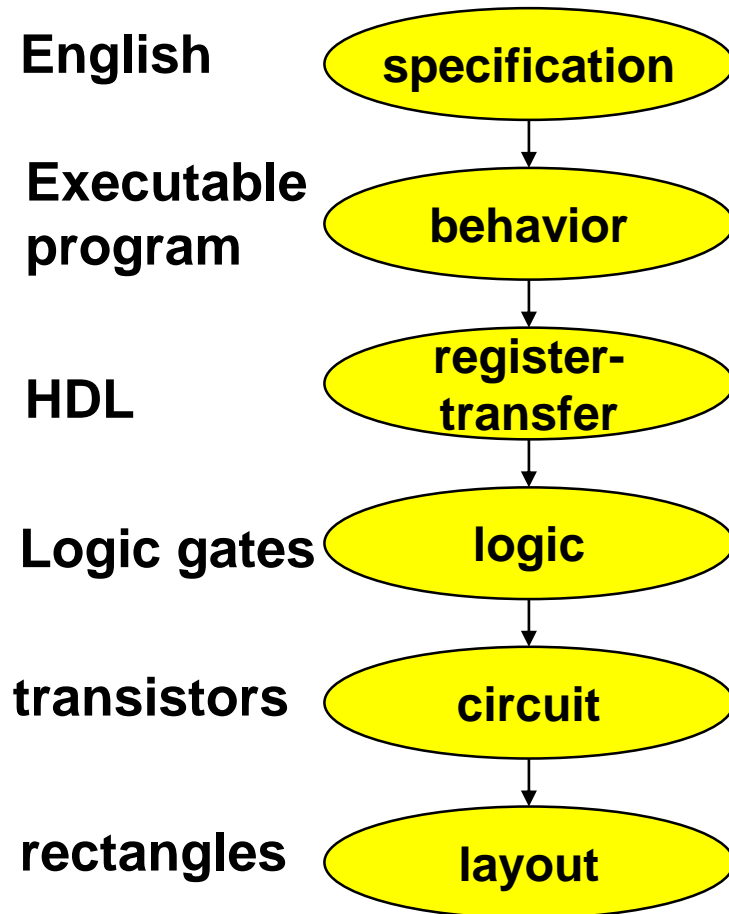
- **Icfb/Dracula, Cadence**
- ICstation/Calibre, Mentor

□ FPGA

- **ISE, Xilinx**
- Quatus, Altera



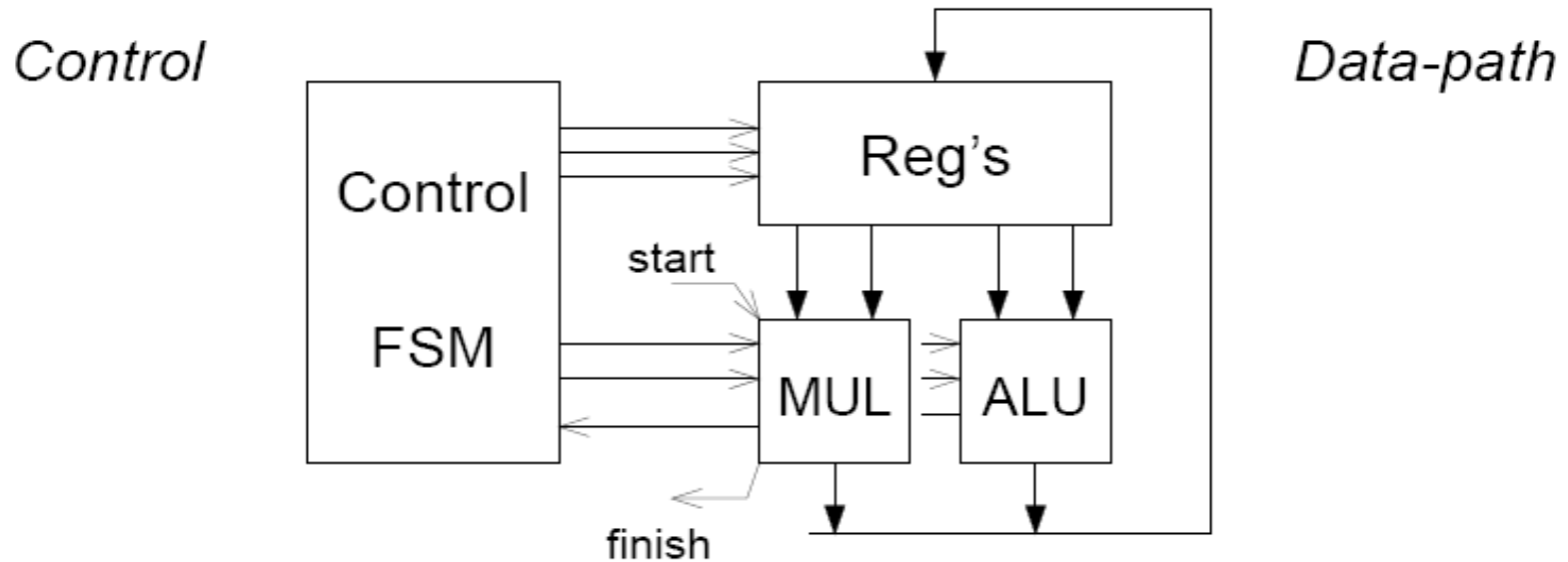
VLSI Design Flow: Summary



Following slides should fresh up your memory



Overall VLSI Structure



□ Scheduling / ordering / sequencing of operations

□ Mapping / allocation:

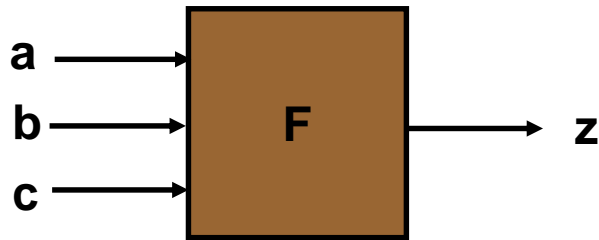
- Variables -> {Reg1, ... ,RegN}
- Operations -> {MUL, ADD, ALU, ... ,}

We will implement something similar in this course



Two Basic Digital Components

Combinational Logic

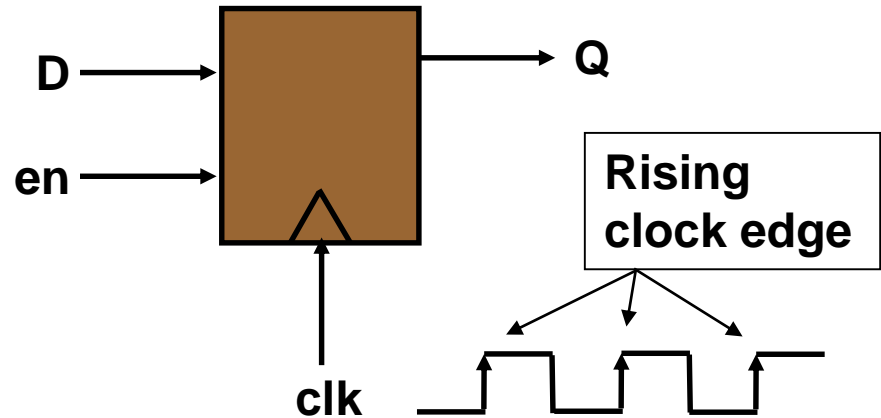


Always:

```
z <= F(a, b, c);
```

i.e. a function that is always evaluated when an input changes.
Can be expressed by a truth table.

Register



```
if clk' event and clk= '1' then  
  if en=' 1' then  
    Q <= D;
```

i.e. a stored variable,
Edge triggered D Flip-Flop
with enable.



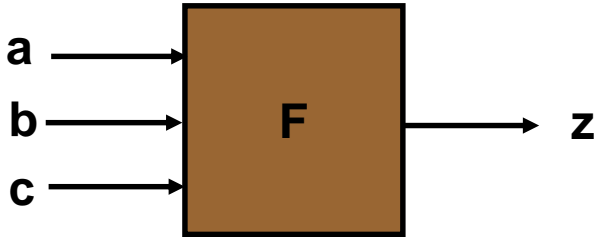
Timing

Only if we guarantee to meet the **timing requirements**

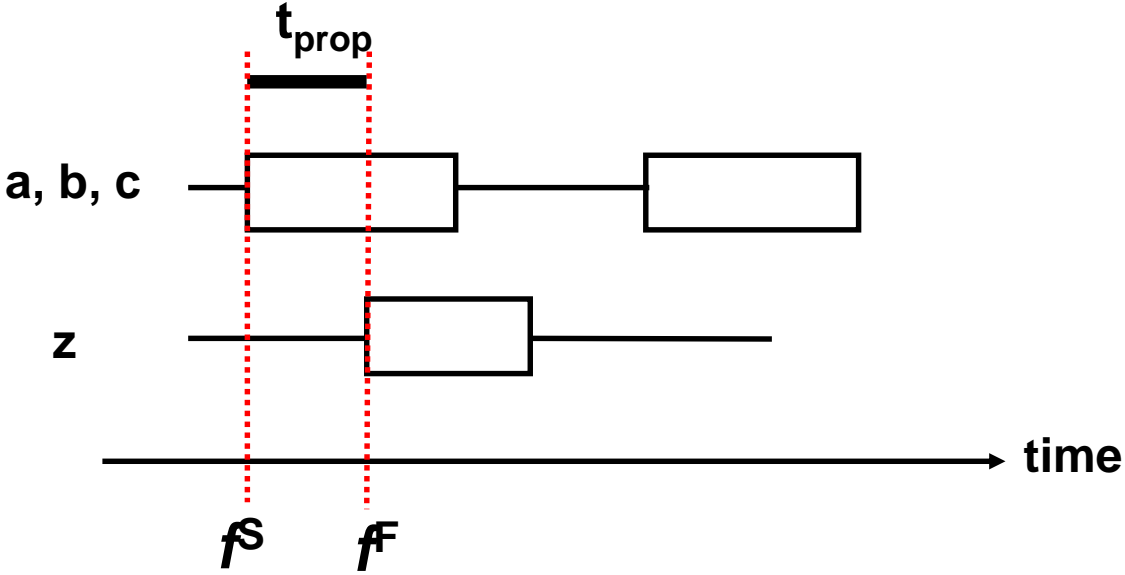
... do the components guarantee to behave as intended.



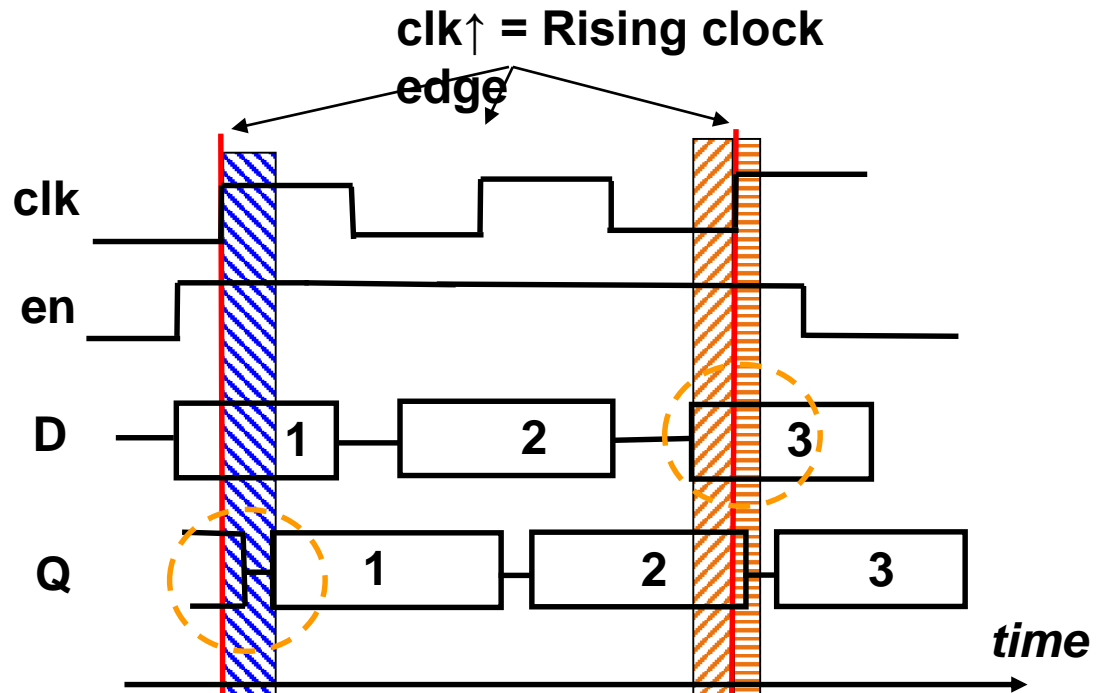
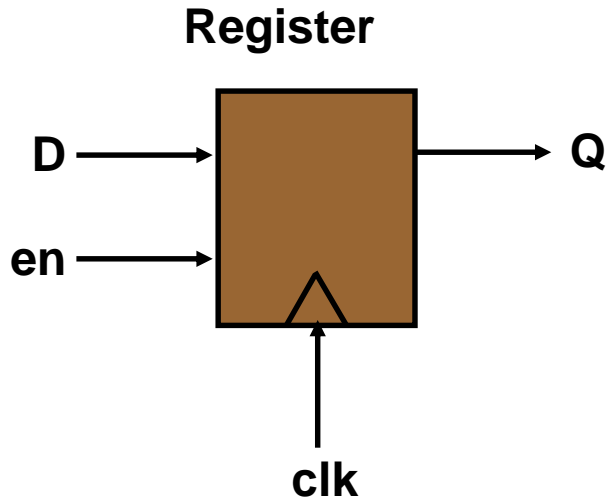
Combinational Logic Timing



- **Propagation delay:**
After presenting new inputs
Worst case delay before
producing correct output



Register timing



Propagation delay (clk_to_Q):
Worst case (maximum) delay after $\text{clk}\uparrow$ before new output data is valid on Q.

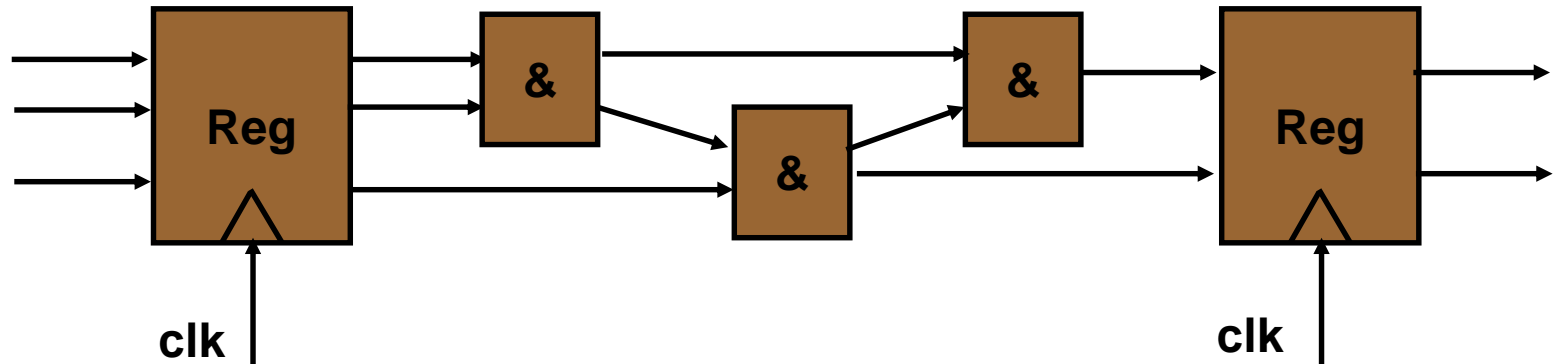
Setup time:
Minimum time input must be stable before $\text{clk}\uparrow$

Hold time:
Minimum time input must be stable after $\text{clk}\uparrow$



Clock Frequency

□ What is the maximum clock frequency?



Register

Propagation delay:	T _{clk-Q}	250ps
Setup time:	T _{su}	200ps
Hold time:	T _h	100ps

AND-gate

Propagation delay:	T _{prop}	250ps
--------------------	-------------------	-------

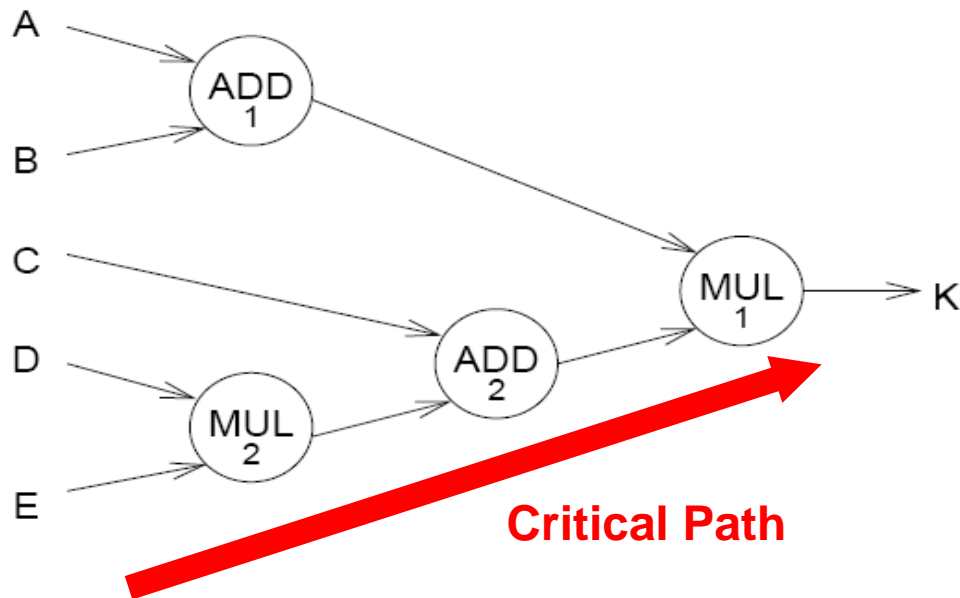
$$250 + 250 * 3 + 200 = 1.2 \text{ns}$$

$$f = 833 \text{MHz}$$



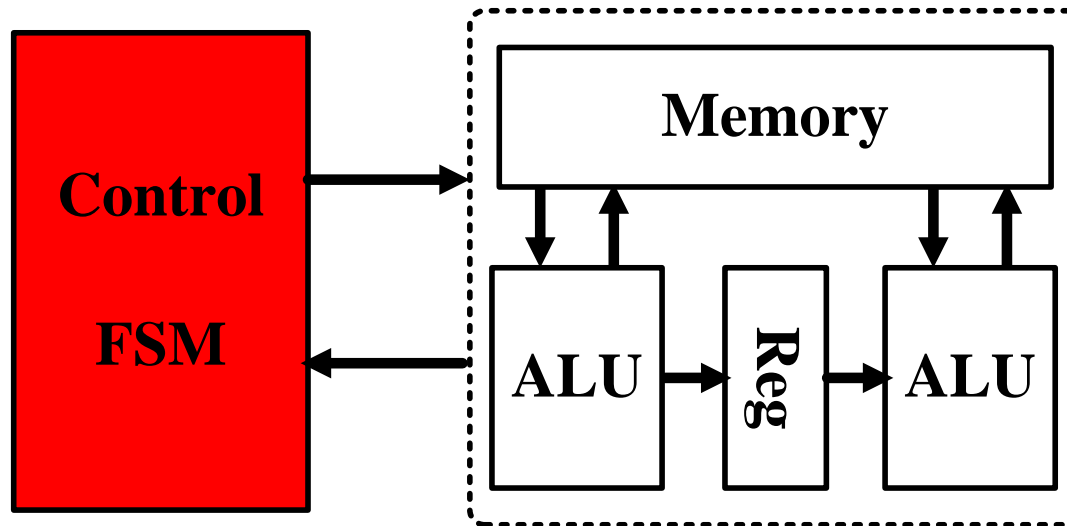
Critical path

- ...begin to explore the construction of digital systems with complex behavior
 - Example: $K = (A +_1 B) *_1 (C +_2 D *_2 E)$
- Combinational circuit:



Tomorrow

- 08:00-10:00 in E:C
- The controller: Finite State Machine
- VHDL Basics
- Assignment 1



Thanks

